



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR TSOP-6					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	40	20 000	200 °C + N2	0	0
HAST	779	77 900	130 °C, 85 % RH	0	0
Pressure Pot	1011	97 056	121°, 15 PSIG	0	0
Solder DUNK	40	120	260 °C, 10 s	0	0
Solderability	15	120	883 M2003	0	0
Temp. Cycle	947	560 724	-55 °C to 150 °C	0	0